ERRATA
TO THE TMS320F206 DSP DATA SHEET
(TEXAS INSTRUMENTS LITERATURE NO. SPRS050A, REVISED APRIL 1998)

Reliability evaluations on DSP Flash technology indicate favorable data retention performance of 10 years [for 55°C application (use) ambient temperature]. This evaluation is based on a limited population of accelerated (non-biased) temperature stress testing, estimations of characteristic data retention failure activation energy, and subsequent calculations from reliability modelling equations. However, no guaranteed data retention performance level is made regarding any material shipped, and any warranty issues are governed by the Texas Instruments Standard Terms and Conditions.

Page: | **Change or Add:**

55   From the *flash EEPROM* section, the switching characteristics over recommended operating conditions table:

- Delete the "Data retention" row (including the MIN value of 10 Years)

Additional Changes

Page: | **Change or Add:**

1

- Change the bulleted item "Three External Interrupts" to read "Four External Interrupts" (INT1–INT3 and NMI)
- Change the bulleted item "On-Chip 16-Bit Timer" to read "On-Chip 20-Bit Timer"

Page: | **Change or Add:**

3   TMS320F206 Terminal Functions table, $\overline{\text{DS}}$ description column:

- Change the following sentence: "$\overline{\text{DS}}$ is always high unless low-level is asserted for communicating to off-chip program space." to "$\overline{\text{DS}}$ is always high unless low level is asserted for communicating to off-chip data space."

Page: | **Change or Add:**

5   TMS320F206 Terminal Functions table, CLKR description column:

- Add the following sentence to the end of the CLKR description: "CLKR goes into the high-impedance state when $\overline{\text{OFF}}$ is active low."

Page: | **Change or Add:**

17   From **Table 7. TMS320F206 Memory Map**

- Change the "x" in the PON[†] column for the 4K × 16 word data single-access RAM (SARAM) to be "0".
- Change the "x" in the DON[†] column for the 4K × 16 word data SARAM to be "0".

DESCRIPTION OF MEMORY BLOCK	DATA MEMORY ADDRESS	PROG MEMORY ADDRESS	MP/$\overline{\text{MC}}$[†]	DON[†]	PON[†]	CNF BIT[†]
4K x 16 word data single-access RAM (SARAM)	0x800 – 0x17FFh		x	1	0	x
4K x 16 word data SARAM		0x8000 – 0x8FFFh	x	0	1	x

[†] "x" denotes don't care condition

Page:	**Change or Add:**

35   From the *documentation support* section:

- Change the following paragraph **from**:

   "For general background information on DSPs and TI devices, see the three-volume publication *Digital Signal Processing Applications With the TMS320 Family* (literature numbers SPRA012, SPRA016, and SPRA017). Also available is the *Calculation of TMS320C2xx Power Dissipation* application report (literature number SPRA088)."

   to:

   "Also available is the *Calculation of TMS320C2xx Power Dissipation* application report (literature number SPRA088)."

Page:	**Change or Add:**

47   From the *READY timing* section, the timing requirements over recommended operating conditions table:

- Change the $t_{v(R-W)}$ MIN value to be a MAX value

		'320F206-40		UNIT
		MIN	**MAX**	
$t_{v(R-W)}$	Valid time, READY after $\overline{WE}$ falling edge		H – 17	ns

Page:	**Change or Add:**

48   From the *XF, TOUT, $\overline{RS}$, $\overline{INT1}$ – $\overline{INT3}$, $\overline{NMI}$, and $\overline{BIO}$ timing* section, the switching characteristics over recommended operating conditions table:

- Change the $t_{d(COL-TOUT)}$ parameter and its description to the following:

PARAMETER		'320F206-40		UNIT
		MIN	**MAX**	
$t_{d(COH-TOUT)}$	Delay time, CLKOUT1 high to TOUT low	0[†]	17	ns

[†] Values specified from characterization data and not tested

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